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Has received an application for a patent for a new and useful invention. The title and description of the invention are enclosed. The requirements of law have been complied with, and it has been determined that a patent on the invention shall be granted under the law.

Therefore, this

United States Patent

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Michelle K. Lee

Director of the United States Patent and Trademark Office

(12) **United States Patent**
Chung et al.

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(54) **LIGHT-EMITTING MODULE**

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 134 days.

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USPC . **362/294**; 362/235; 362/311.02; 362/311.04;
257/98; 257/100; 257/712

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See application file for complete search history.

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(57) **ABSTRACT**

A light-emitting module includes a heat-dissipating structure, a multichip package structure and a protection cover structure. The multichip package structure is disposed on the heat-dissipating structure, and the multichip package structure includes a substrate unit, a light-emitting unit, a frame unit and a package unit. The protection cover structure is disposed on the heat-dissipating structure to cover and protect the multichip package structure, and the protection cover structure has an opening for exposing the package unit.

16 Claims, 10 Drawing Sheets

